MA27V09

Silicon epitaxial planar type

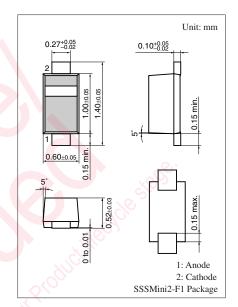
For VCO

■ Features

- ullet Good linearity and large capacitance-ratio in $C_D V_R$ relation
- High frequency type by this low capacitance
- SSS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	6	V
Junction temperature	Tj	125	°C
Storage temperature	T _{stg}	-55 to +125	°C



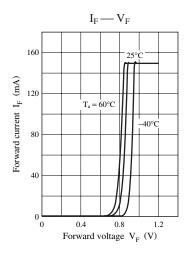
Marking Symbol: 9

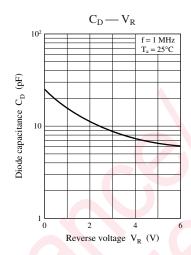
■ Electrical Characteristics $T_a = 25$ °C ± 3°C

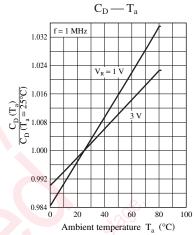
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I_R	$V_R = 5 \text{ V}$	1000	0,,	10	nA
Diode capacitance	C _{D(1V)}	$V_R = 1 \text{ V, } f = 1 \text{ MHz}$	14.9	5-	16.4	pF
	$C_{D(3V)}$	$V_R = 3 \text{ V, f} = 1 \text{ MHz}$	8.4		9.2	
Capacitance ratio	C _{D(1V)} /C _{D(3V)}	95: 67: 10	1.69		1.87	_
Series resistance *	r_{D}	$V_R = 3 \text{ V, } f = 470 \text{ MHz}$			0.35	Ω

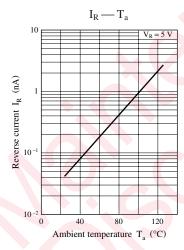
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. Absolute frequency of input and output is 470 MHz.
- 3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER









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